

AMENDMENTS

IN THE CLAIMS

Please amend the following Claims as shown below:

1. (original) A packaged semiconductor device comprising:
 - a first semiconductor die disposed over a package substrate, said first semiconductor die coupled to said package substrate;
 - a plurality of wire bonds coupled said first semiconductor die and coupled to said package substrate for electrically coupling said first semiconductor die to said package substrate;
 - a first layer of encapsulant disposed over said first semiconductor die and disposed over said plurality of wire bonds; and
 - a second semiconductor die disposed over said first layer of encapsulant and coupled to said first layer of encapsulant, said second semiconductor die electrically coupled to said package substrate.
2. (original) The packaged semiconductor device of Claim 1 wherein said second semiconductor die is directly coupled to said first layer of encapsulant using adhesive.
3. (original) The packaged semiconductor device of Claim 2 wherein said second semiconductor die at least partially overlies said first semiconductor die.

Application No.: 10/649,123

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Attorney Docket No.: IDT-1742.DIV

Filed: 8/27/2003

Received 10-14-2003

Claims
Renumbered
per 37 CFR 1.126
S.W.S.
3-3-2004

4. (currently amended) The packaged semiconductor device of Claim 2 wherein only portions of said first layer of encapsulant, portions of said plurality of wire bonds and said adhesive extend between said first semiconductor die and said second semiconductor die, ~~and above an internal region of the top surface of said first semiconductor die, said internal region including that portion of the top surface of said first semiconductor die that lies inside of any bonding pads that are disposed within said top surface of said first semiconductor die.~~

5. (original) The packaged semiconductor device of Claim 2 wherein no spacer is disposed between said first semiconductor die and said second semiconductor die.

6. (original) The packaged semiconductor device of Claim 2 wherein said package substrate is a ball grid array package substrate.

7. (currently amended) The packaged semiconductor device of Claim 6 ~~wherein said plurality of wire bonds comprise a first set of wire bonds, said packaged semiconductor device further comprising:~~

~~a second~~ an additional set of wire bonds, said additional set of wire bonds coupled to said second semiconductor die and coupled to said ball grid array package substrate for electrically coupling said second semiconductor die to said ball grid array package substrate; and

a second layer of encapsulant disposed over said second semiconductor die and disposed over said ~~second~~ additional set of wire bonds.

8. (original) The packaged semiconductor device of Claim 1 wherein said adhesive comprises a silver-filled epoxy adhesive.

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~~9.~~ (new) A packaged semiconductor device comprising:

a first semiconductor die disposed over a package substrate, said first semiconductor die coupled to said package substrate;

a plurality of wire bonds coupled said first semiconductor die and coupled to said package substrate for electrically coupling said first semiconductor die to said package substrate;

a first layer of encapsulant disposed over said first semiconductor die and disposed over said plurality of wire bonds; and

a second semiconductor die disposed over said first layer of encapsulant, said second semiconductor die attached to said first layer of encapsulant using adhesive, said second semiconductor die electrically coupled to said package substrate.

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~~10.~~ (new) The packaged semiconductor device of Claim ²¹~~9~~ wherein said second semiconductor die at least partially overlies said first semiconductor die.

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~~11.~~ (new) The packaged semiconductor device of Claim ²¹~~9~~ wherein only portions of said first layer of encapsulant, portions of said plurality of wire bonds and said adhesive extend between said first semiconductor die and said second semiconductor die.

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~~12.~~ (new) The packaged semiconductor device of Claim ²¹~~9~~ wherein no spacer is disposed between said first semiconductor die and said second semiconductor die.

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13. (new) The packaged semiconductor device of Claim ~~12~~ wherein said package substrate is a ball grid array package substrate.

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14. (new) The packaged semiconductor device of Claim ~~8~~ further comprising:
an additional set of wire bonds, said additional set of wire bonds coupled to said second semiconductor die and coupled to said package substrate for electrically coupling said second semiconductor die to said package substrate.

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15. (new) The packaged semiconductor device of Claim ~~14~~ further comprising:
a second layer of encapsulant disposed over said second semiconductor die and disposed over said additional set of wire bonds.

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16. (new) The packaged semiconductor device of Claim ~~8~~ wherein said adhesive comprises a silver-filled epoxy adhesive.

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17. (new) A packaged semiconductor device comprising:
a first semiconductor die disposed over a package substrate, said first semiconductor die coupled to said package substrate;
a first set of wire bonds coupled said first semiconductor die and coupled to said package substrate for electrically coupling said first semiconductor die to said package substrate;
a first layer of encapsulant disposed over said first semiconductor die and disposed over said first set of wire bonds;

a second semiconductor die disposed over said first layer of encapsulant, said second semiconductor die attached to said first layer of encapsulant using adhesive; and

a second set of wire bonds, said second set of wire bonds coupled to said second semiconductor die and coupled to said package substrate for electrically coupling said second semiconductor die to said package substrate.

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18. (new) The packaged semiconductor device of Claim ~~17~~ further comprising:

a second layer of encapsulant, said second layer of encapsulant disposed over said second semiconductor die and disposed over said second set of wire bonds.

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19. (new) The packaged semiconductor device of Claim ~~17~~ wherein only portions of said first layer of encapsulant, portions of said first set of wire bonds and said adhesive extend between said first semiconductor die and said second semiconductor die.

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20. (new) The packaged semiconductor device of Claim ~~17~~ wherein no spacer is disposed between said first semiconductor die and said second semiconductor die.